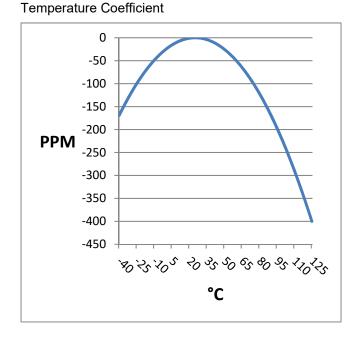


3.2 x 1.5mm Auto Grade Tuning Fork

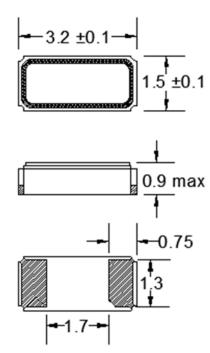
K13A (former FXA135) DATASHEET

- AEC-Q200 Qualified
- IATF-16949 QMS

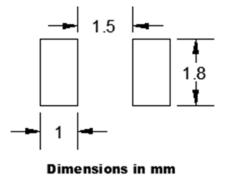
| STANDARD SPECIFICATIONS | | | | | | |
|------------------------------------|--------------------------------|--|--|--|--|--|
| PARAMETERS | MAX (unless otherwise noted) | | | | | |
| Frequency | 32.768 kHz | | | | | |
| Frequency Tolerance @ 25°C | (See options on page 2.) | | | | | |
| Frequency Stability | | | | | | |
| (Temperature Coefficient) | -0.04 PPM / (Δ°C) ² | | | | | |
| Temperature Range | | | | | | |
| Turnover (T ₀) | +20°C ~ +30°C | | | | | |
| Operating (T _{OPR}) | -40°C ~ +125°C | | | | | |
| Storage (T _{stg}) | -55°C ~ +125°C | | | | | |
| Equivalent Series Resistance (Rs) | 70 kΩ | | | | | |
| Load Capacitance (C _L) | (See options on page 2.) | | | | | |
| Insulation Resistance @ 100VDC | 500MΩ Min | | | | | |
| Drive Level | 1.0uW | | | | | |
| | 0.1uW Typ | | | | | |
| Aging per year @ 25°C (first year) | ±3 PPM | | | | | |
| Maximum Soldering Temp / Time | 260°C / 10 Seconds x2 | | | | | |
| Moisture Sensitivity Level (MSL) | 1 | | | | | |
| Termination Finish | Au over Ni | | | | | |
| Seal Method | Seam | | | | | |
| Lead (Pb) Free | Yes | | | | | |
| RoHS/Reach Compliant | Yes | | | | | |



Page 1 of 3



Recommended Solder Pad Layout



Note: Dimensional drawing is for reference to critical specifications defined by size measurements. Certain non-critical visual attributes, such as side castellations, etc. may vary.

| 222 | Title / Description: K13A STANDARD SPECIFICATIONS | | | |
|---|---|---------------|---------------------------|--|
| FÖX | Drawing Number: K13A-I | Size: A | | |
| FOX | Part Number: | Cage: 61429 | | |
| © Copyright 2019 Fox Electronics. All rights reserved | Draftsperson: MAJ | Approved: BEC | Revision Date: 08/05/2019 | |



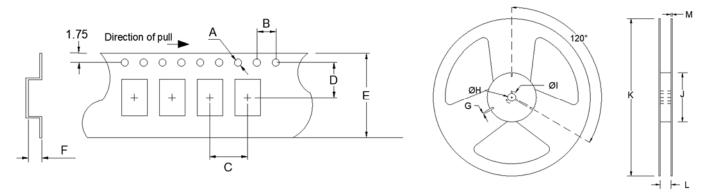
3.2 x 1.5mm Auto Grade Tuning Fork

K13A

(former FXA135)
DATASHEET

Page 2 of 3

| TAPE SPECIFICATIONS (millimeters) | | | REEL SPECIFICATIONS (millimeters) | | | | | | | | | | |
|-----------------------------------|-----|-----|-----------------------------------|------|-----|-------------|-----|-----|-----|-----|------|------|-----|
| Α | В | С | D | E | F | Reel QTY | G | Н | I | J | K | L | M |
| Ø1.55 | 4.0 | 4.0 | 5.5 | 12.0 | 1.0 | -T3 = 3,000 | 2.0 | Ø13 | Ø21 | Ø60 | Ø180 | 13.0 | 1.2 |



Available Options & Part Identification for SMD Tuning Fork Crystal K13A F K13A F I H I 0.032768

| F | K13A | E | I | Н | 1 | 0.032768 |
|-----|------------------------|--|--|--|---|--------------------|
| FOX | Model <u>Number</u> | Tolerance E = ±20 PPM H = ±10 PPM L = ±5 PPM | <u>Stability</u> I =-0.04 PPM / (Δ°C) ² | Load <u>Capacitance</u> B = 6pF V = 7pF W = 9pF H = 12.5pF | Operating <u>Temperature</u> I = -40 ~ +125°C | Frequency (MHz) |



Corporate Headquarters

5570 Enterprise Parkway Fort Myers, FL 33905 http://www.FOXONLINE.com

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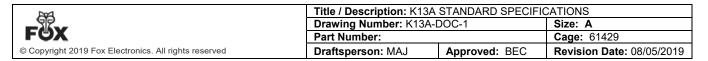
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Page 3 of 3



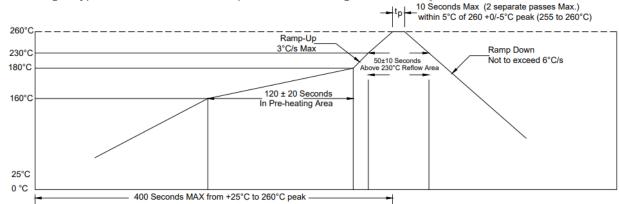
Crystal Unit Handling Precautions

1) Mounting Precautions

- If the board is deformed, such as bending after mounting, peeling of the soldered joint between the crystal resonator and board may occur producing a crack in the ceramic package, leading to loss of vacuum, destruction of the internal element, etc. Especially when depaneling the board on which it is mounted, there is a possibility that a large stress may be applied, please consider board layout and cutting method to minimize stress on products.
- When the product is automatically mounted on the board, if a large impact is applied to the crystal resonator, there is a possibility that characteristics may change / deteriorate, or the product may be broken. When mounting automatically, please set conditions considering the shock to the crystal unit. Also, please conduct the mounting test beforehand and confirm that there is no influence on the characteristics to the crystal resonator.
- Cracks may occur in the soldered part by repeated harsh temperature changes for a long time when mounting due to the board having a expansion coefficient different from that of the ceramics used in the crystal package. When using under such circumstances, please conduct test beforehand and confirm that there is no influence on the crystal unit.
- Ceramic packages are small and thin products. So, if/when you rework after mounting, please give consideration to the selection and handling of the tools to be used.

2) Soldering





Excessive heating time at high temperature may result in deterioration of the characteristics and may break the crystal unit. For manual rework, heat the lead part at 300°C or lower for 5 seconds or less.

3) Cleaning

Since a small, thin crystal chip is used for tuning fork crystal units and the frequency approximates that of an ultrasonic cleaner, the crystal chip may break easily. Therefore, DO NOT perform ultrasonic cleaning.

| 22 | Title / Description: K13A STANDARD SPECIFICATIONS | | | | |
|---|---|---------------|---------------------------|--|--|
| | Drawing Number: K13A-I | Size: A | | | |
| FÖX | Part Number: | Cage: 61429 | | | |
| © Copyright 2019 Fox Electronics. All rights reserved | Draftsperson: MAJ | Approved: BEC | Revision Date: 08/05/2019 | | |